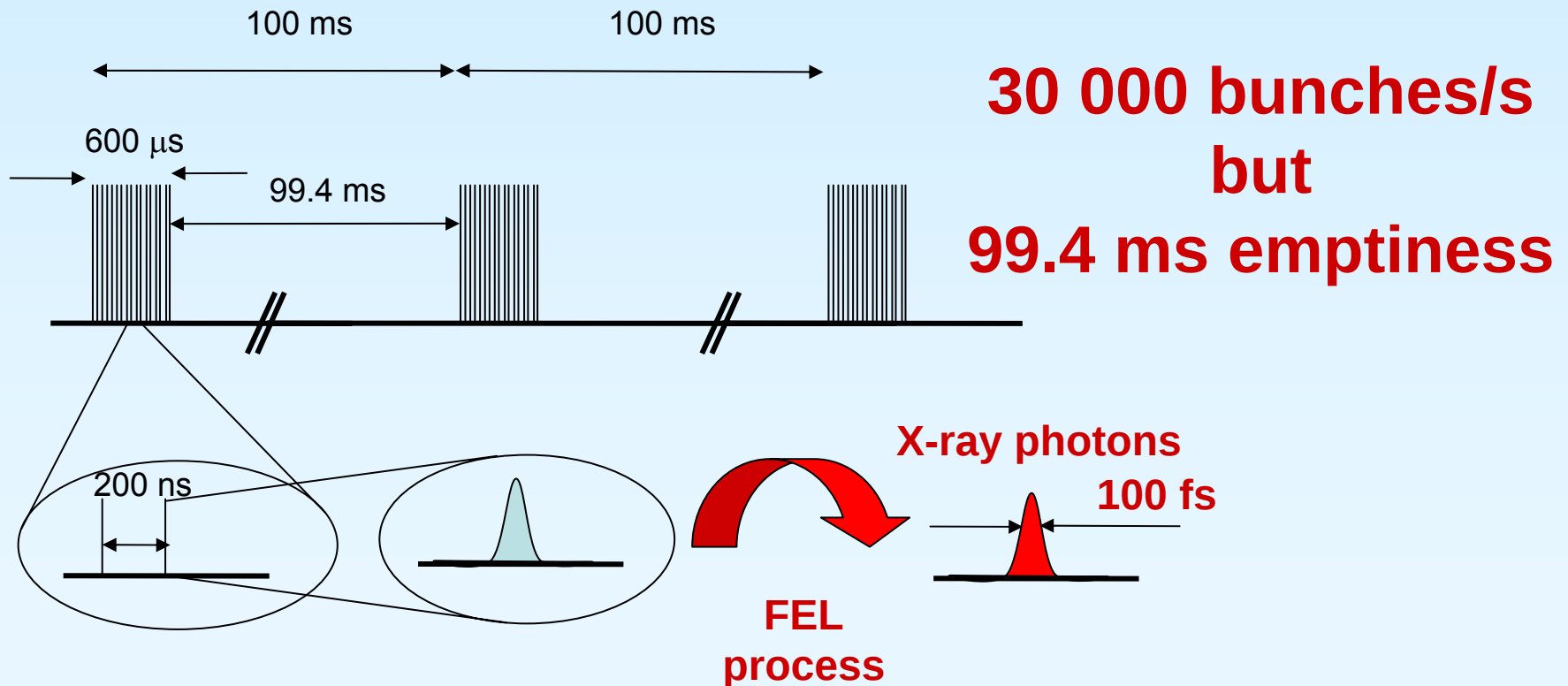


X-ray Detectors at DESY

Heinz Graafsma
DESY

Time structure: difference with “others”

Electron bunch trains; up to 3000 bunches in 600 μs , repeated 10 times per second.
Producing 100 fsec X-ray pulses (up to 30 000 bunches per second).



Consequences of Time structure

- Either: $< 10\text{Hz}$ or $> 1.5\text{ kHz}$; best 5 MHz
- All photons arrive in 100 fsec → integrating detectors.
- Experiments should profit from high luminosity ($30\,000\text{ shots/sec}$).
- Every shot is a new experiment (jitter, sample destruction,..)

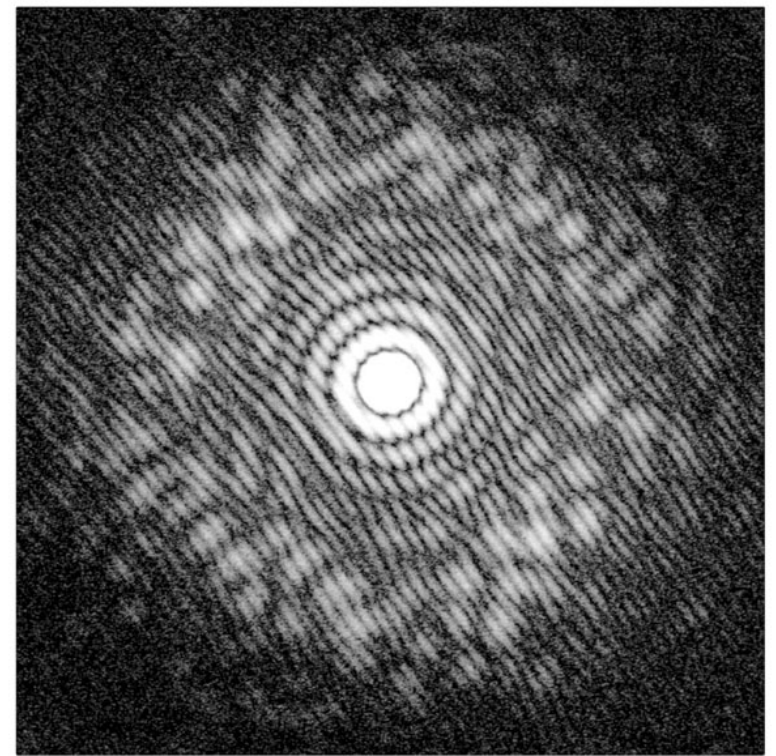
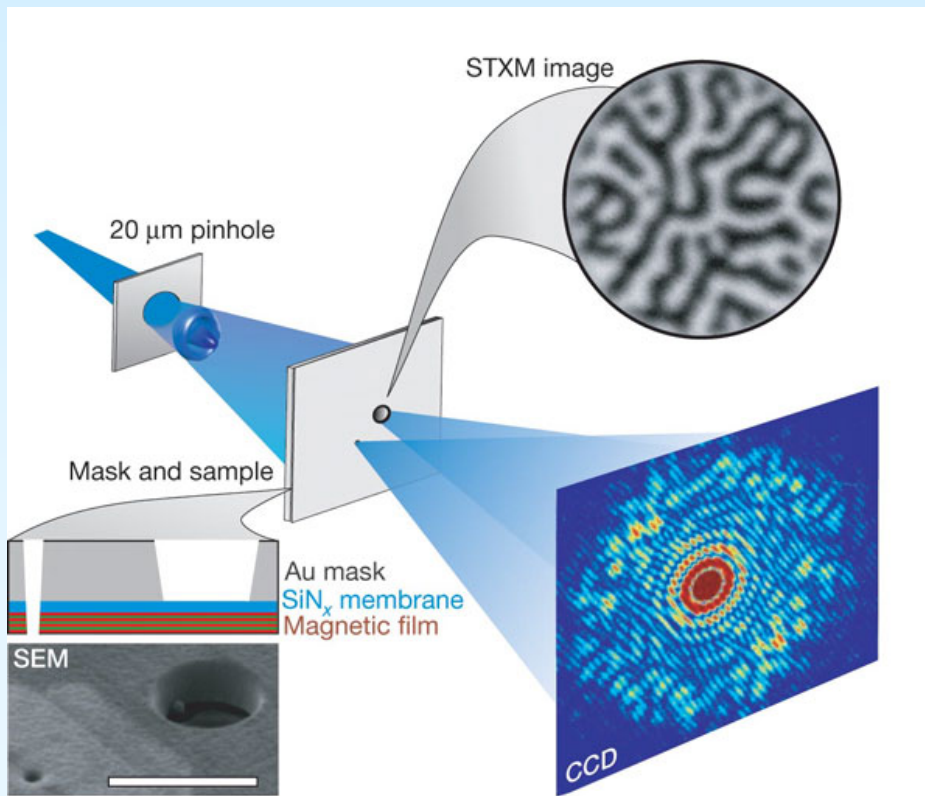
- TDR has 8 different application areas
- 5 areas need 2D X-ray detectors:
 - Pump-Probe non-crystalline diffraction
 - Pump Probe crystalline diffraction
 - Coherent Diffraction Imaging
 - Single Particle Imaging
 - X-ray Photon Correlation Spectroscopy

Typical requirements:

Direct Holographic Inversion

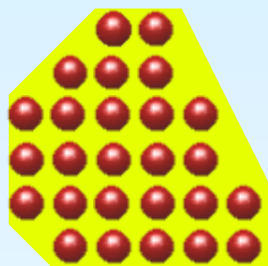
1.59nm RCP diffraction from magnetised film and pinhole

S. Eisebitt, J. Lüning, W. Schlotter, M. Lörger, O. Hellwig, W. Eberhardt and J. Stöhr, Nature 432, 885-888 (2004)

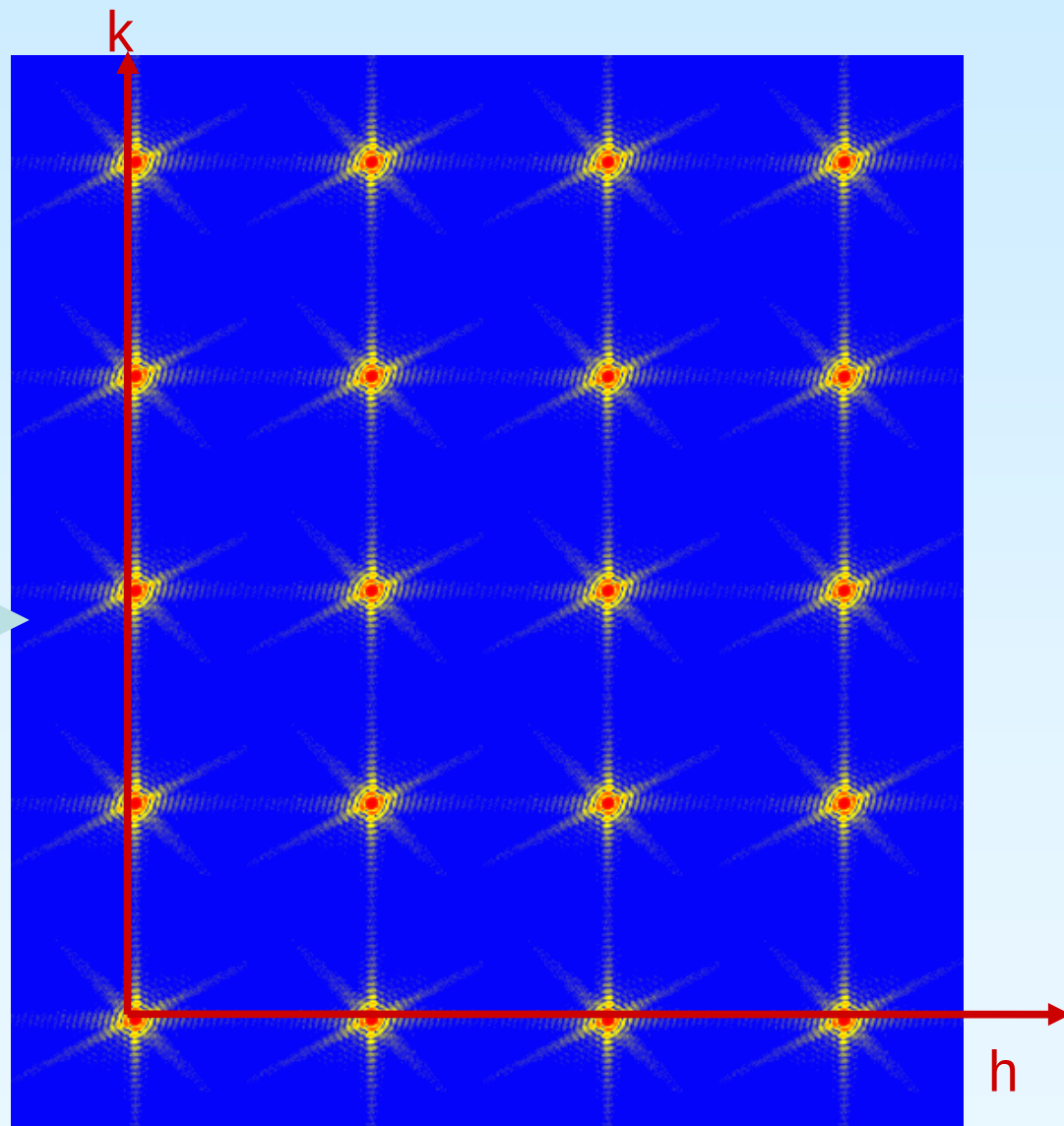


Typical requirements:

Coherent Diffraction from Crystals



Fourier Transform



• <u>DETECTOR CDI:</u>	MUST
• Total detector angle	120 degrees
• Pixel Size	0.1 mrad
• Number of Pixels	10k x 10k
• Single photon resolution	yes (Poisson limit)
• Tiling tolerated	yes
• Signal rate/pixel/bunch	up to 10^6
• Timing	luminosity optimized
• Photon energy range [keV]	8-12
• Quantum efficiency	>0.8
• Environment	vacuum (input window ?)
• Radiation Hardness	10^{16} X-rays
• Harmonics Discrimination	no

How to solve this?

Hybrid Pixel Array Detector (HPAD)

Diode Detection Layer

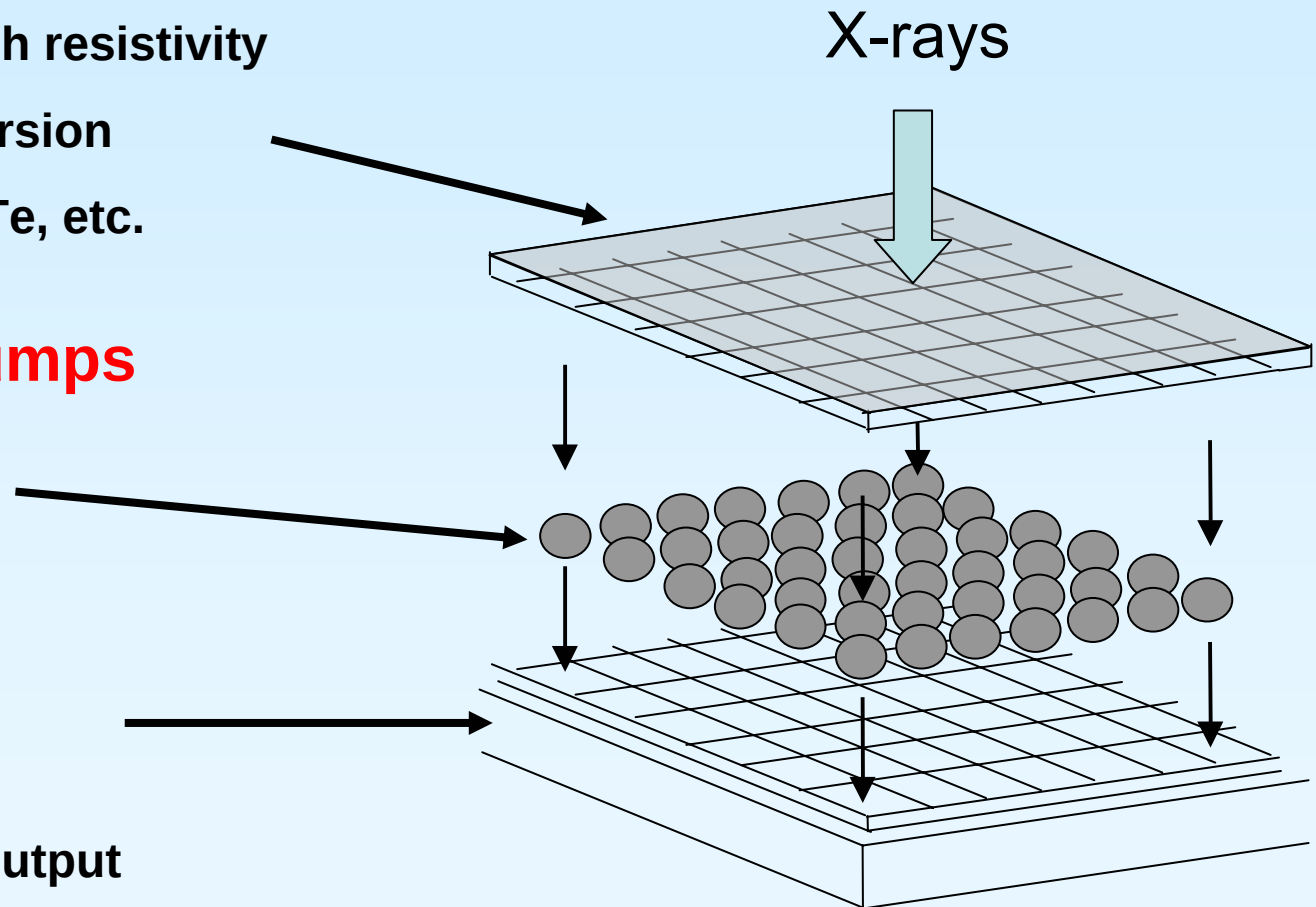
- Fully depleted, high resistivity
- Direct x-ray conversion
- Silicon, GaAs, CdTe, etc.

Connecting Bumps

- Solder or indium
- 1 per pixel

CMOS Layer

- Signal processing
- Signal storage & output



Gives enormous flexibility!

Analog Pipeline Pixel Chip (Broenniman)

Basic idea:

- Integrating system
- Configurable analog frontend
- Store images of micro-bunches on caps in the pixels (5MHz switching)
- Readout the images during the 100ms gap

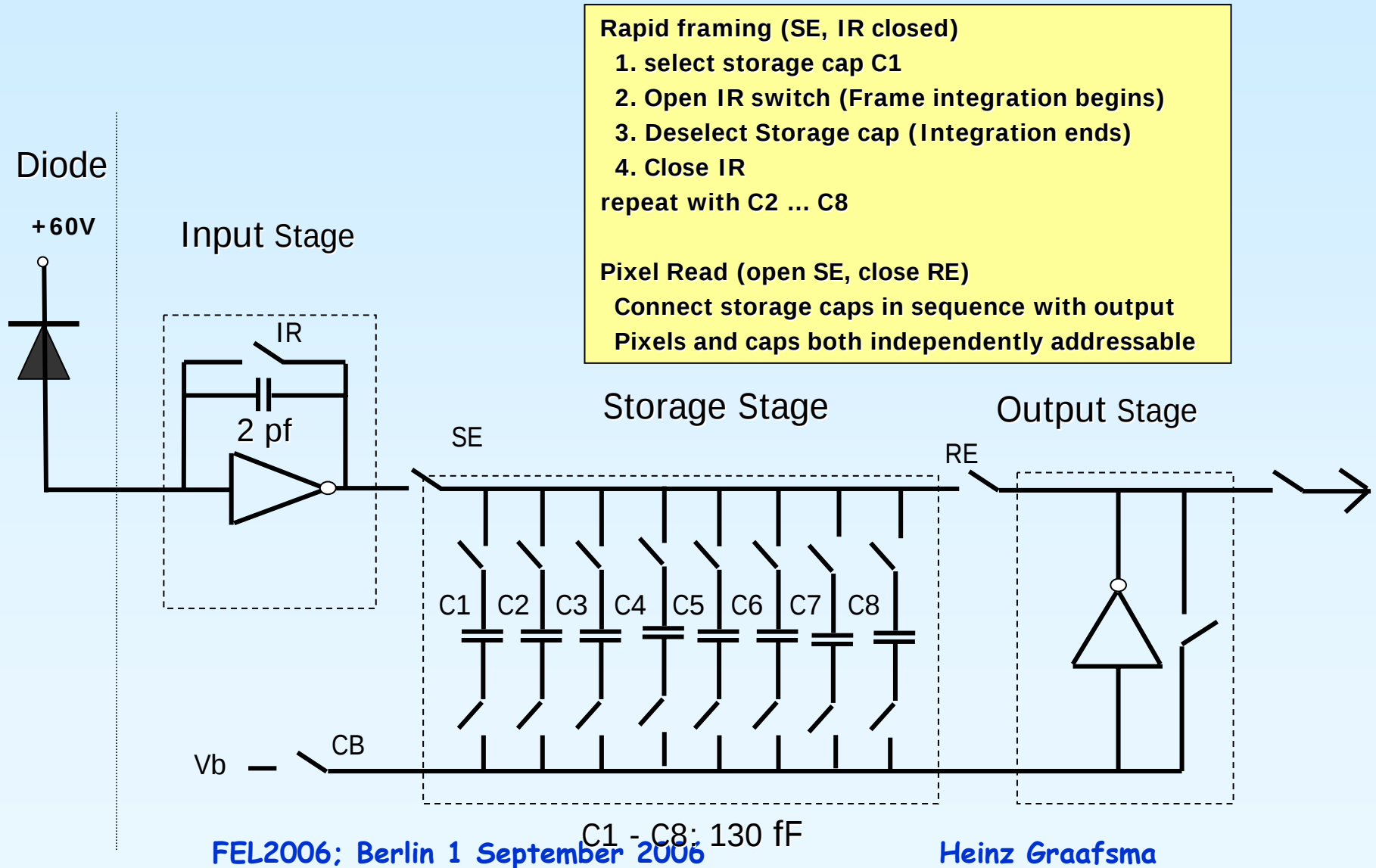
Predecessor Chips:

HEP: H1 strip Analog Pipeline Chip (APC), CMS & Atlas strip and others

X-ray Pixel: APAD Cornell

We do not start from scratch

...



X-ray beam

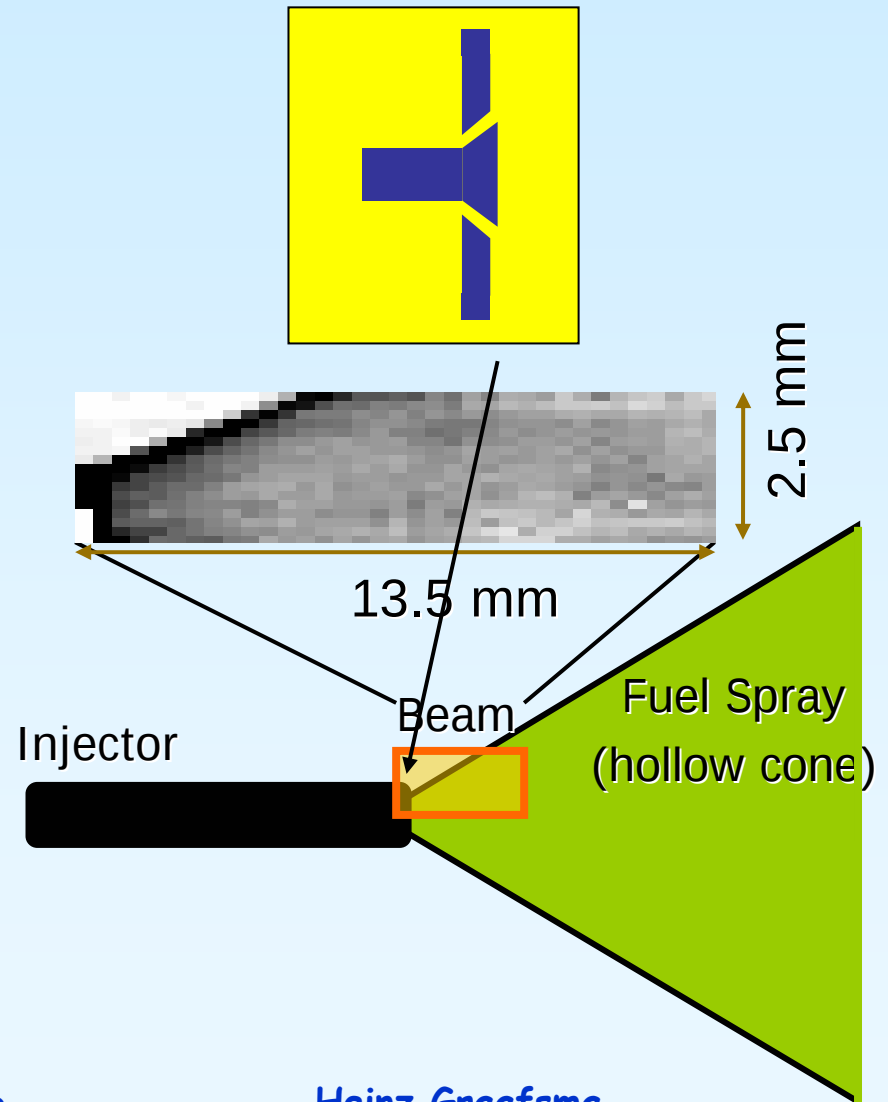
- CHESS Beamline D-1
- 6 keV (1% bandpass)
- 2.5 mm x 13.5 mm
- (step sample to tile large area)
- 10^9 x-rays/pix/s
- 5.13 μ s integration (2x ring period)

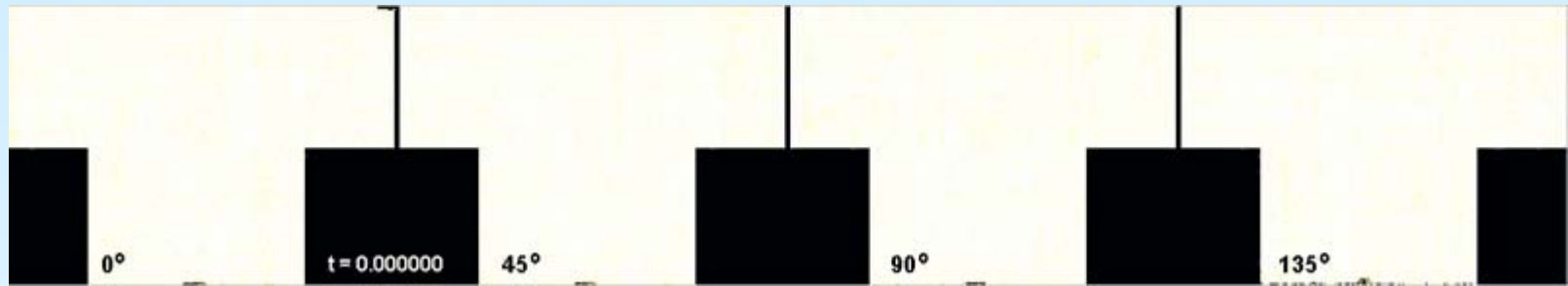
Fuel injection system

- Cerium added for x-ray contrast
- 1000 PSI gas driven
- 1 ms pulse
- 1 ATM Nitrogen

Collaboration: Jin Wang (APS) & S.M. Gruner (Cornell)

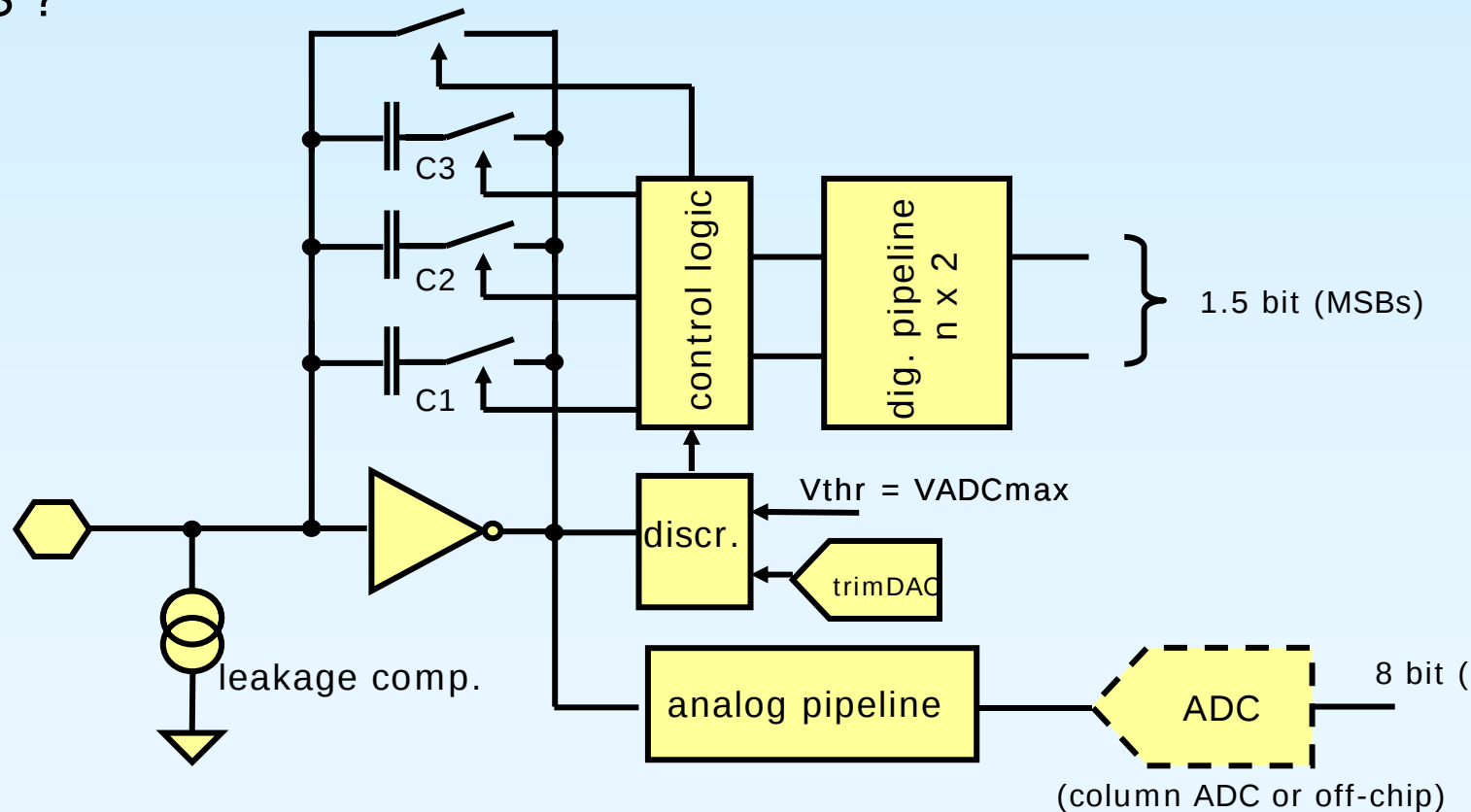
See: Cai, Powell, Yue, Narayanan, Wang, Tate, Renzi, Ercan, Fontes & Gruner
Appl. Phys. Lett. 83 (2003) 1671.



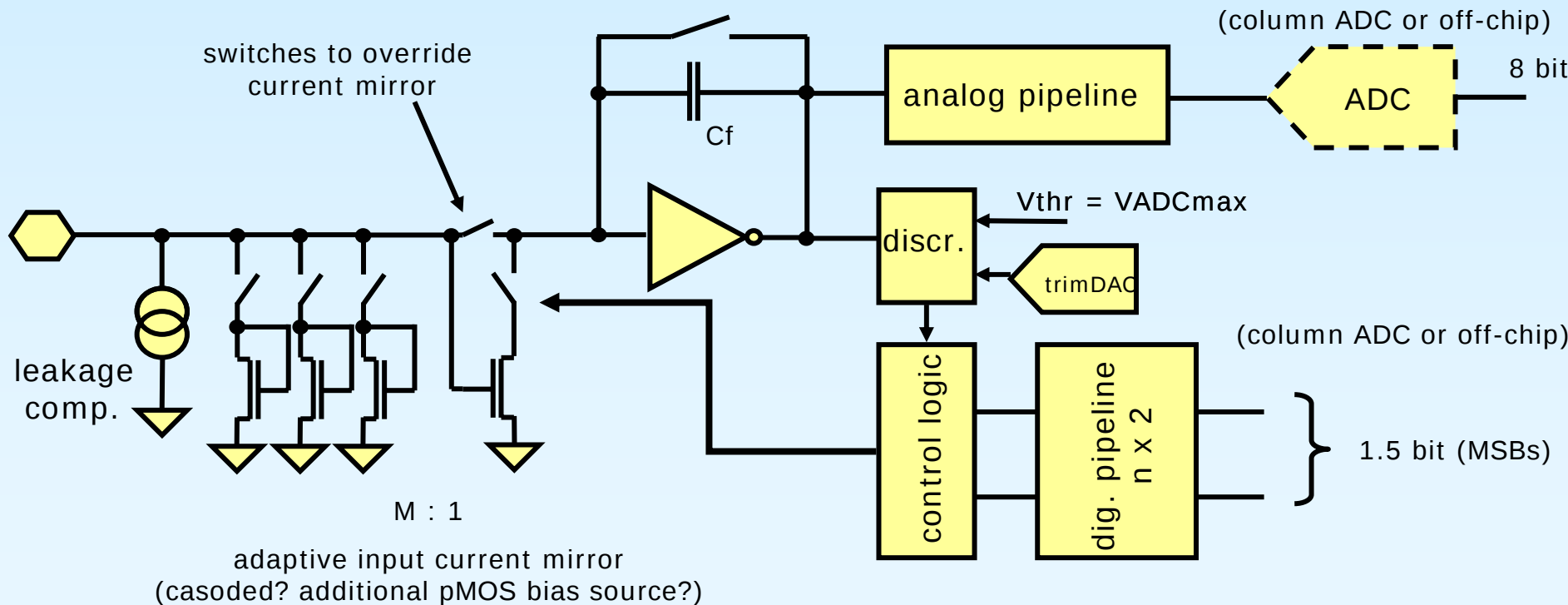


- 1.8 ms time sequence (composite). 10^5 images
- $5.13 \mu\text{s}$ exposure time. ($15.4 \mu\text{s}$ between frames)
- 88 frames (11 groups of 8 frames), Avg. 20x for noise.
- 1000 x-rays/pixel/ μs
- Data taken with 4 projections.

- wide dynamic input range
- multiple (3) scaled feedback capacitors
- reduced ADC resolution (8 bit instead of 10 bit)
- analog + digital (2 bit) pipeline
- in-pixel CDS ?



- keep C_f fixed
- scale input current with configurable current mirror: $M_i = 1, 16, 64 \dots$
- increase dynamic range beyond 10^4 ($i > 3$)
- could be implemented in less area



Rough dimensions:

~ 20 μm^2 / cap cell ->

1000 caps (frames) ~ 140 x 140 μm^2 -> Pixel size ~ 160 x 160 μm^2

500 caps (frames) ~ 100 x 100 μm^2 -> Pixel size ~ 120 x 120 μm^2

100 caps (frames) ~ 44 x 44 μm^2 -> Pixel size ~ 65 x 65 μm^2

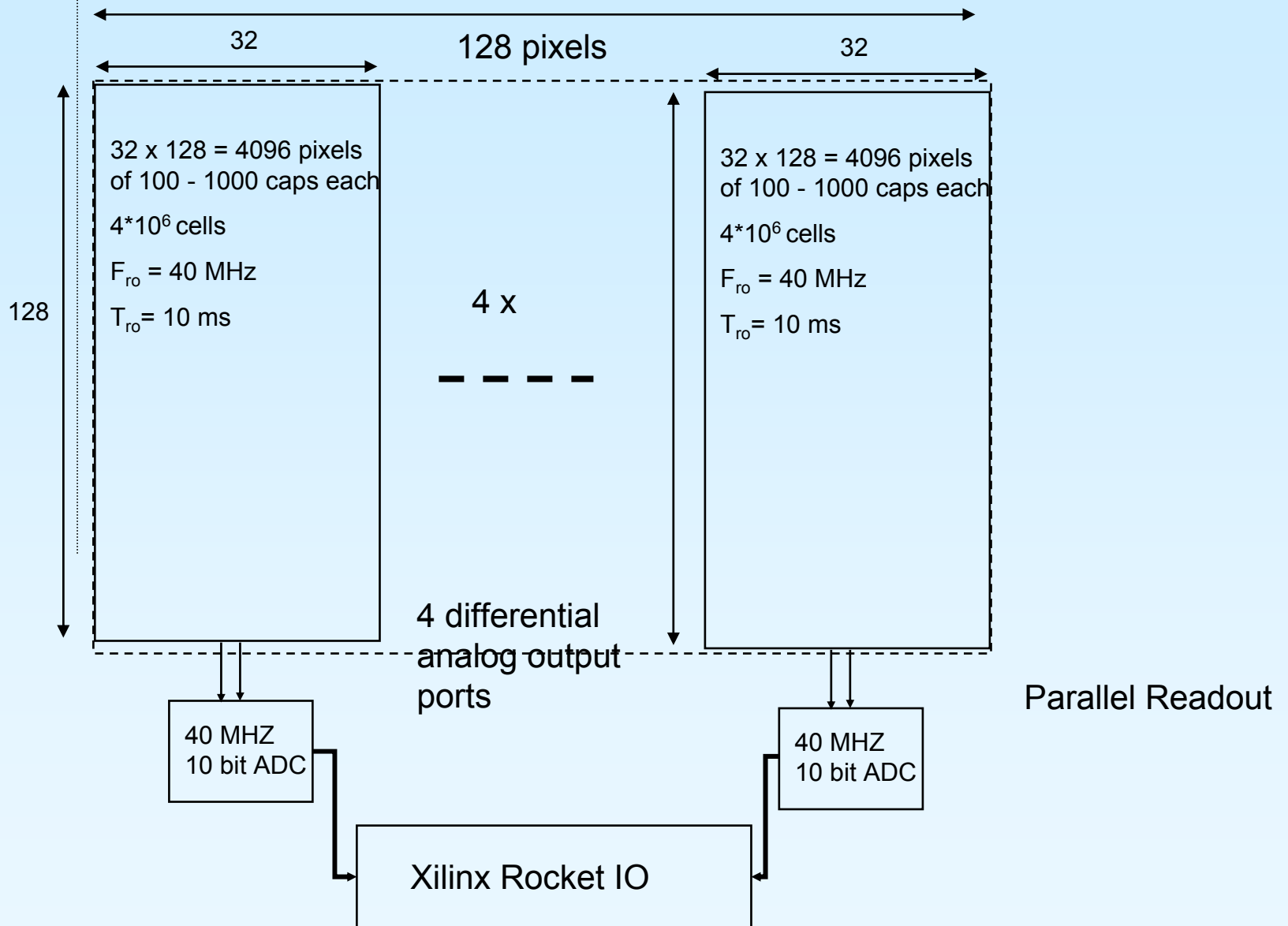
Readout system:

Programmable and flexible pipeline control (Off Chip):

Number of X-ray pulses to be stored before readout (1, 10, or n-frames)

Adding of X-ray pulses (2 together, every 3rd pulse, ...)

Analog Pipeline Pixel: Chip Architecture

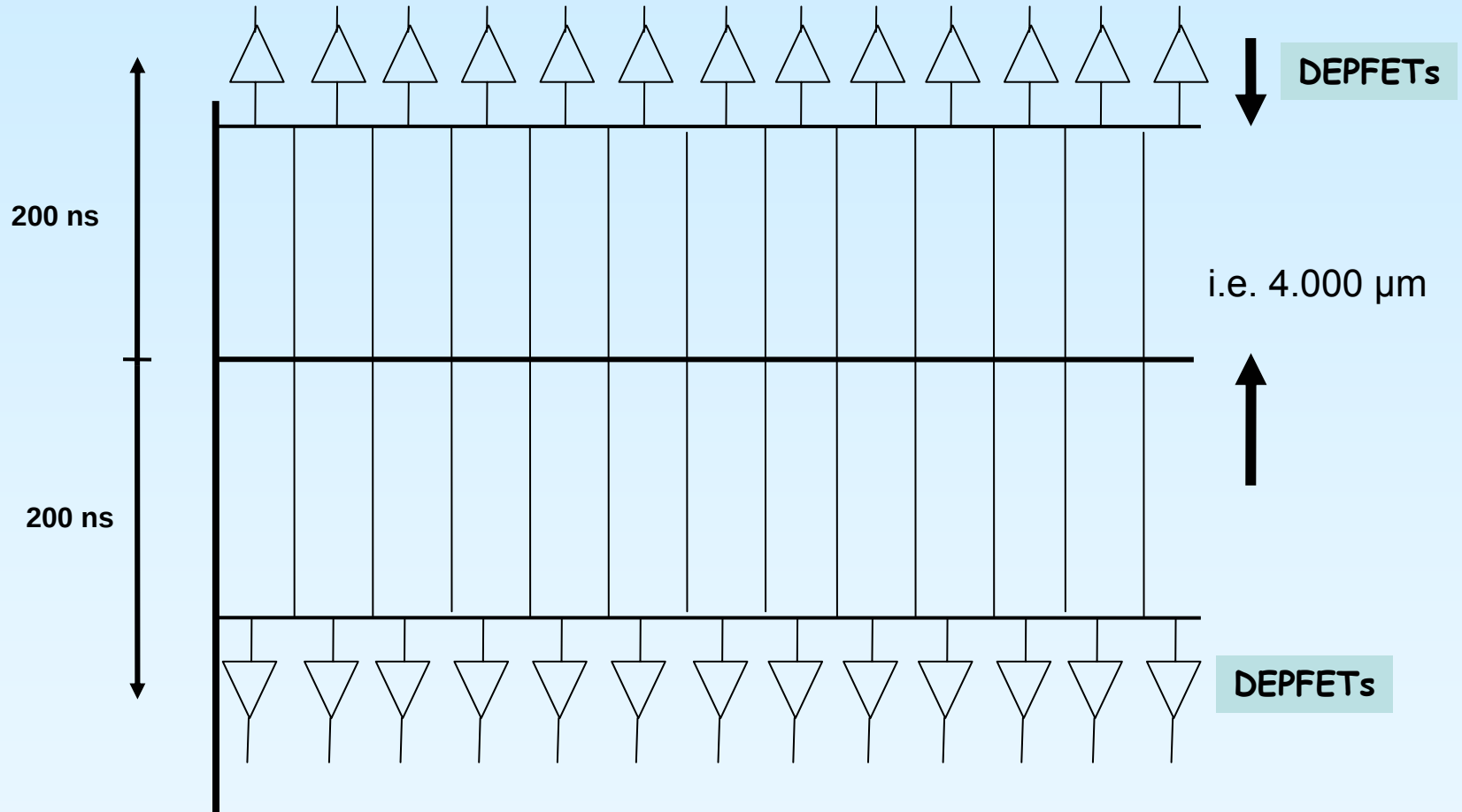


Hybrid Pixel Array Detector (HPAD)

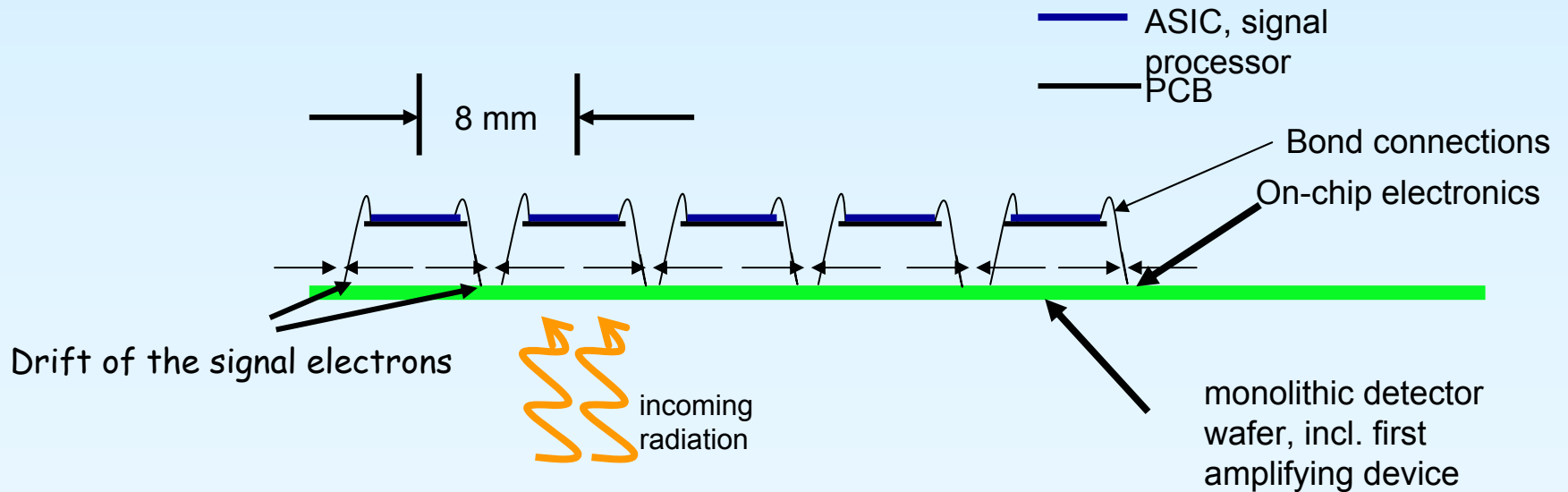
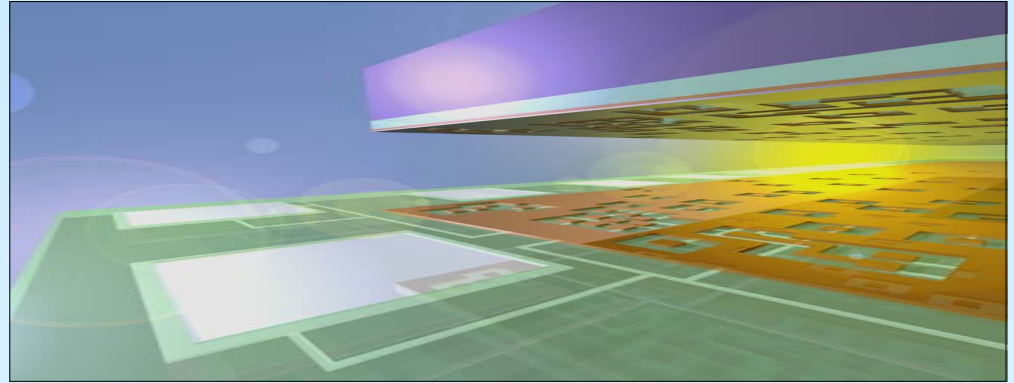
Courtesy Christian Broennimann



- Silicon Drift Detectors (with DEPFET's)

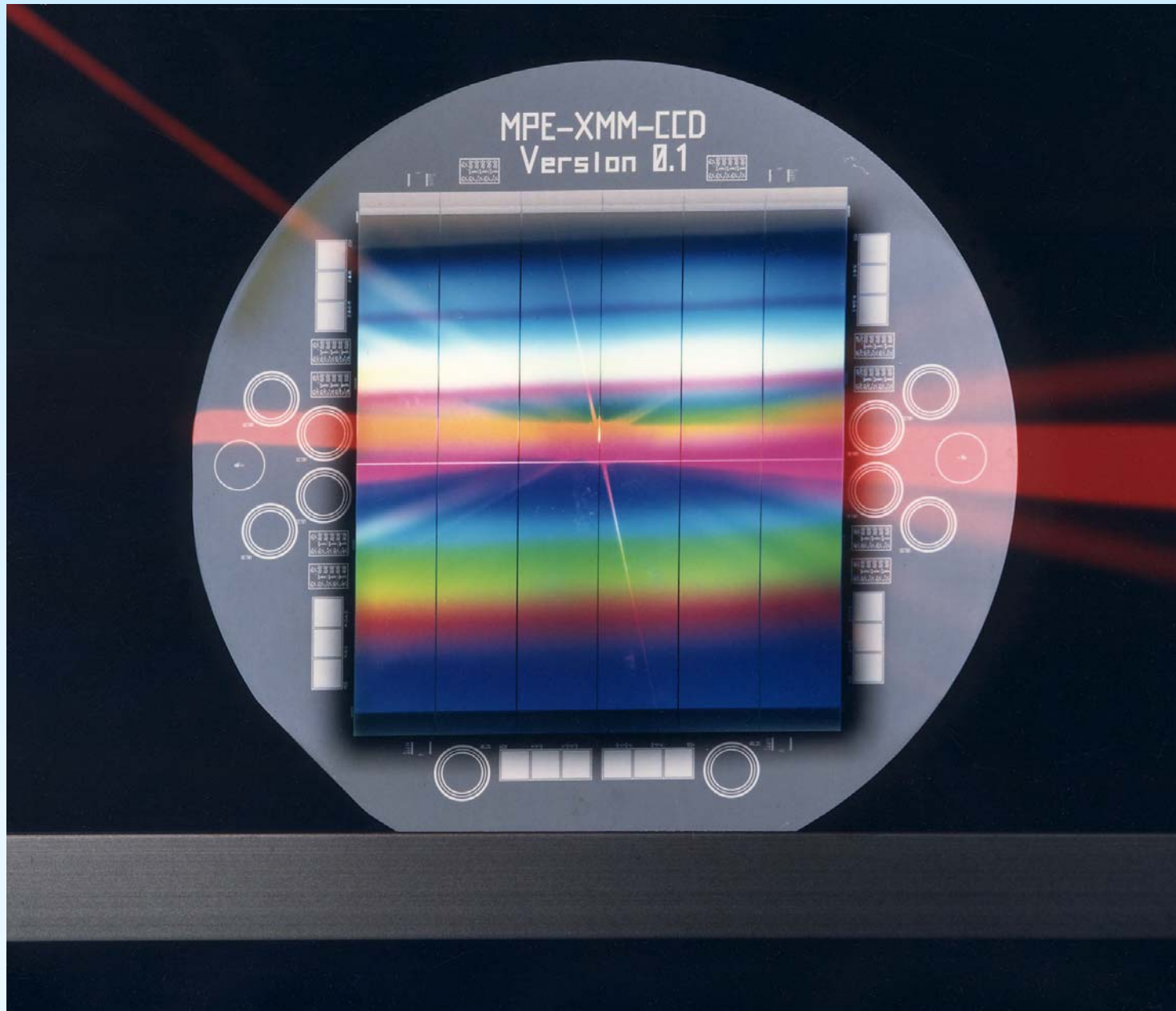


$V_{\text{max}} \approx 100 \mu\text{m} / \text{ns}$, $V_{\text{exp}} \approx 20 \mu\text{m} / \text{ns}$ That means: $\Delta t = 3 \text{ ns}$, $\Delta x = 60 \mu\text{m}$
 total area_{max}: $80 \times n \cdot 8 \text{ mm}^2$, CHC: unlimited (almost)



The XMM chip

Courtesy Lothar Strueder



Some of the challenges

- Large **dynamic range** with low noise (gain switching may be needed)
- **Radiation** hardness (in 3 years up to 10^{16} photons per pixel)
- High **instantaneous flux** (10^4 X-rays in 100 fsec in a few micron of Si)
- Storing **3000 images** inside pixel, while keeping pixel small (100 micron)
- Very high overall **data rate**
-

European XFEL Project Team

c/o Deutsches Elektronen-Synchrotron DESY
in der Helmholtz-Gemeinschaft,
Notkestraße 85,
D-22607 Hamburg, Germany

**XFEL****X-Ray Free-Electron Laser**

Call by the:

European Project Team for the X-ray Free-Electron Laser

for:

Expressions of Interest

to:

Develop and Deliver Large Area Pixellated X-ray Detectors.

Deadline: 30 September 2006

<http://xfel.desy.de/xfelhomepage>